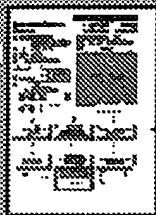


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Inventor(s):

YASUDA MASAYUKI

Applicant(s):

SONY CORP

Issued/Filed Dates:

Oct. 9, 1998 / March 21, 1997

Application Number:

JP1997000068383

IPC Class:

H05K 003/06; H05K 001/09;

Abstract:

Problem to be solved: To form a thin wiring in a simple environment by removing a prescribed part of a resist film by laser abrasion after the resist film showing a resistance to etching is formed on metal foil to serve as conductors and successively resolving the resist and wet-etching the metal foil.

Solution: After an etching resist 3 is formed on metal foil, the etching resist is removed by projecting a laser beam 4 upon the conductor removing part of the laminated body from the resist 3 side. Then a desired wiring board is obtained by performing etching on the substrate with resolved resist thus obtained. The resolved resist is stripped off by using a stripping-off solution. Therefore, a printed wiring board can be manufactured in a simple environment without paying attention to the influence of dust, etc.

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Foreign References:

none

(No patents reference this one)

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(19)

(11) Publication number: **10**

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PATENT ABSTRACTS OF JAPAN

(21) Application number: **09068383**(51) Intl. Cl.: **H05K 3/06 H05K 1/09**(22) Application date: **21.03.97**

(30) Priority:

(43) Date of application
publication: **09.10.98**(84) Designated contracting
states:(71) Applicant: **SONY CORP**(72) Inventor: **YASUDA MASAYUKI**

(74) Representative:

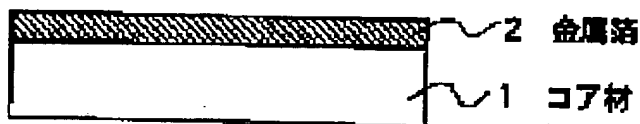
(54) MANUFACTURE OF PRINTED WIRING BOARD

(57) Abstract:

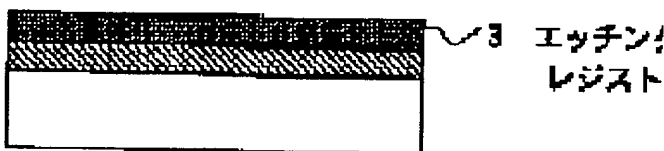
PROBLEM TO BE SOLVED: To form a thin wiring in a simple environment by removing a prescribed part of a resist film by laser abrasion after the resist film showing a resistance to etching is formed on metal foil to serve as conductors and successively resolving the resist and wet-etching the metal foil.

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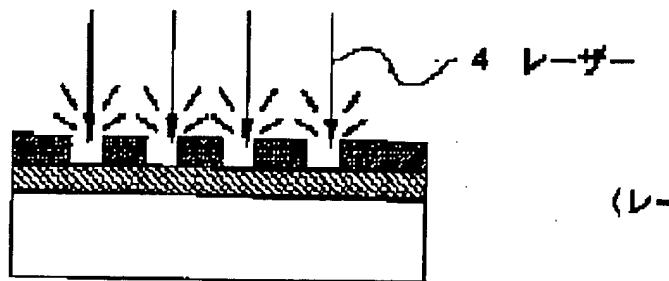
(a)



(b)



(c)



(d)



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environment without paying
attention to the influence of dust, etc.

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